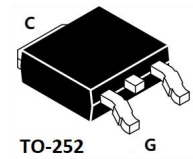


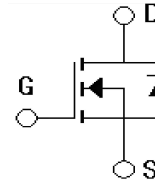
## Features

- $V_{DS}=60V, I_D=30A$   
 $R_{DS(ON)}=35m\Omega @ V_{GS}=10V$
- LOW  $R_{DS(ON)}$
- Super High Dense Cell Design
- Reliable and rugged



## Applications

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Management



## Absolute Ratings (TC=25°C unless otherwise specified)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DSS}$	60	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current-continuous <sup>(1)</sup>	$I_D$	$T_C=25^\circ C$	30
		$T_C=100^\circ C$	21
Drain Current-pulse <sup>(2)</sup>	$I_{DM}$	120	A
Single Pulsed Avalanche Energy <sup>(3)</sup>	$E_{AS}$	16	mJ
Maximum Power Dissipation	$P_D$	$T_C=25^\circ C$	50
		$T_C=100^\circ C$	25
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	°C

## Electrical Characteristics (TC=25°C unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
Drain-Source Voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0V$	60	65	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=V_{DSS}, V_{GS}=0V, T_C=25^\circ C$	-	-	1	$\mu A$
		$T_C=125^\circ C$	-	-	50	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On-Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.8	1.3	2.0	V
Static Drain-Source On-Resistance <sup>(4)</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=12A$	-	35	45	m $\Omega$

Dynamic Characteristics <sup>(5)</sup>						
Input capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHZ$	-	2700	-	pF
Output capacitance	$C_{oss}$		-	1016	-	pF
Reverse transfer capacitance	$C_{rss}$		-	487	-	pF

**Electrical Characteristics**( $T_{CASE}=25^{\circ}C$  unless otherwise specified)

Parameter	Symbol	Tests conditions	Min	Typ	Max	Units
<b>Switching-Characteristics<sup>(5)</sup></b>						
Gate Resistance	$R_G$	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	25	-	$\Omega$
Turn-On delay time	$t_{d(on)}$	$V_{DS}=28V, I_D=16A,$ $V_{GS}=15V, R_G=25\Omega$	-	52	-	ns
Turn-On rise time	$t_r$		-	142	-	ns
Turn-Off delay time	$t_{d(off)}$		-	355	-	ns
Turn-Off rise time	$t_f$		-	230	-	ns
Total Gate Charge	$Q_g$		$V_{DS}=48V, I_D=16A,$ $V_{GS}=10V, R_G=25\Omega$	-	19	-
Gate-Source charge	$Q_{gs}$	-		6.3	-	nC
Gate-Drain charge	$Q_{gd}$	-		4.8	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Maximum Continuous Drain-Source Diode Forward Current <sup>(4)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=16A$	-	0.73	1.2	V
Diode Forward Current	$I_S$		-	-	30	A
Reverse recovery time	$T_{rr}$	$I_{SD}=15A,$ $di_{SD}/dt=100A/\mu s$	-	100	-	nS
Reverse recovery charge	$Q_{rr}$		-	0.33	-	$\mu C$

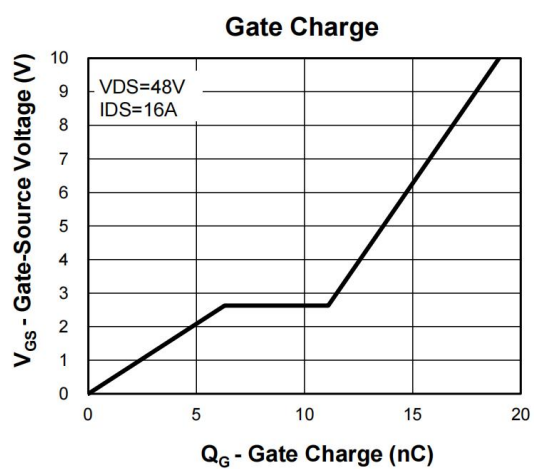
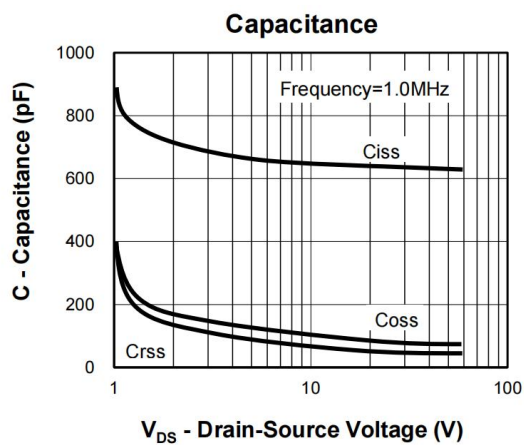
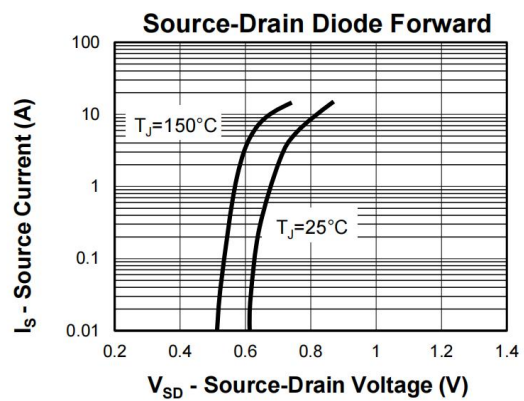
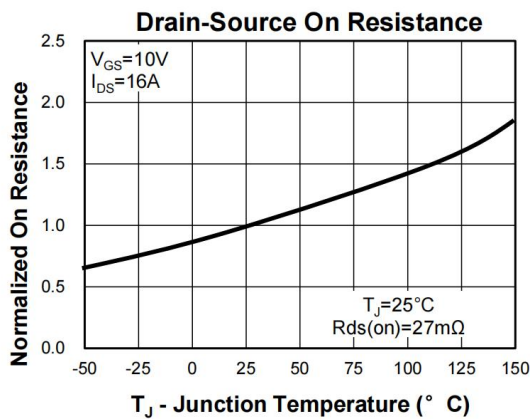
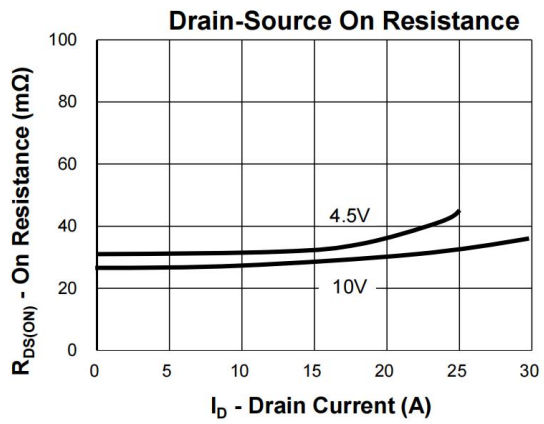
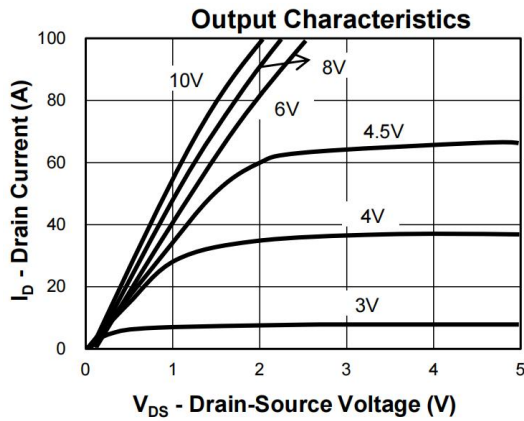
**Thermal Characteristic**

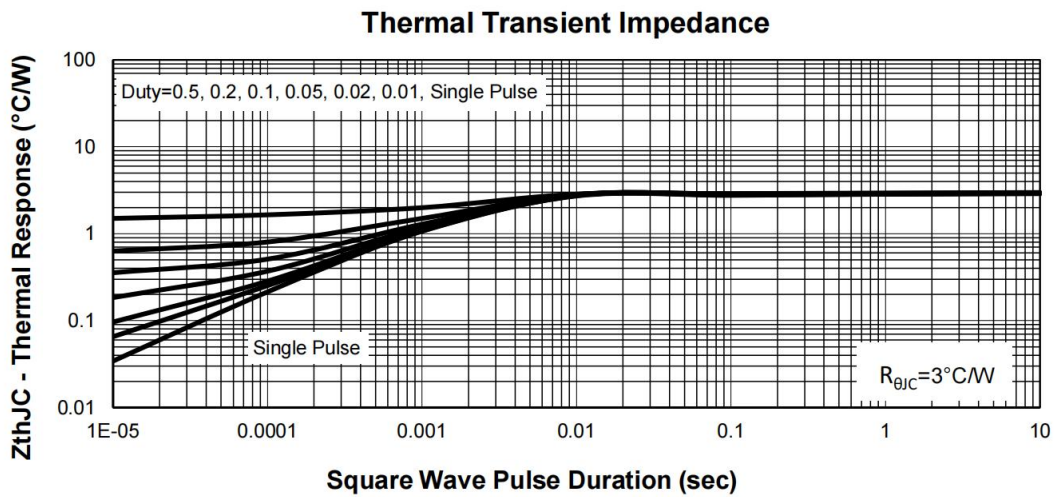
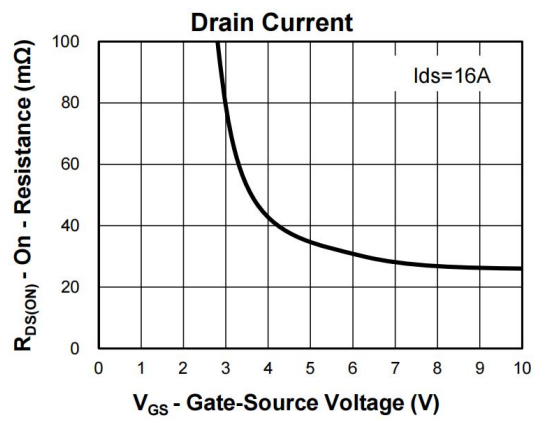
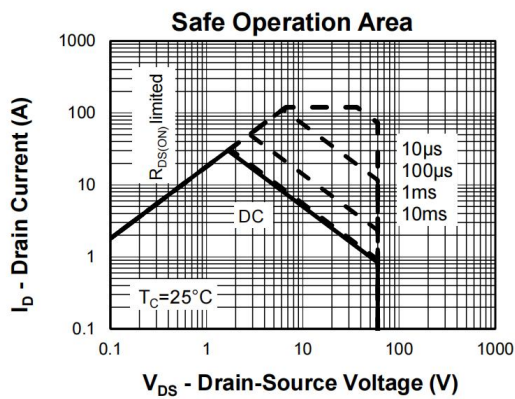
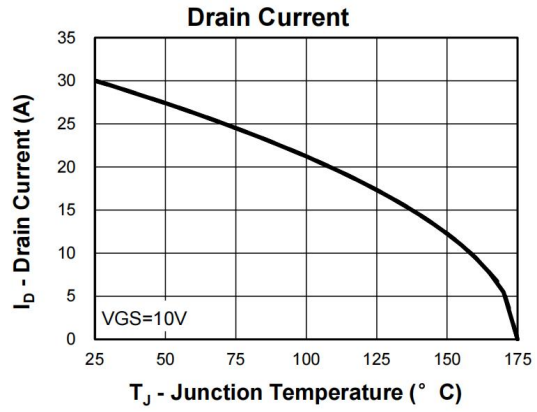
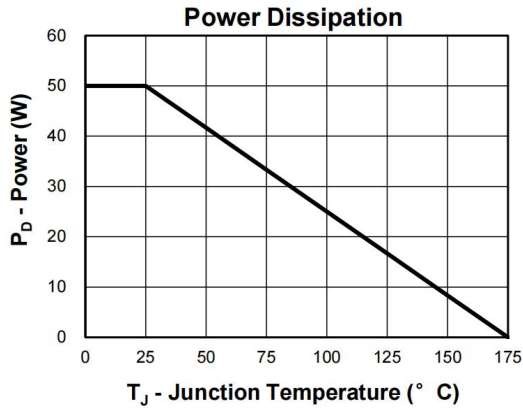
Parameter	Symbol	Value	Unit
Thermal Resistance, junction to Case	$R_{th(j-C)}$	3	$^{\circ}C/W$
Thermal Resistance, junction to Ambient <sup>(6)</sup>	$R_{th(j-A)}$	100	$^{\circ}C/W$

Notes:

1. Calculated continuous current based on maximum allowable junction temperature.
2. Pulse width limited by safe operating area.
3. Limited by  $T_{Jmax}$ ,  $I_{AS}=8A$ ,  $L=0.5mH$ ,  $V_{DD}=30V$ ,  $R_G=25\Omega$ , Starting  $T_J=25^{\circ}C$ .
4. Pulse test; Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. Guaranteed by design, not subject to production testing.
6. When mounted on 1 inch square copper board,  $t \leq 10sec$ . The value in any given application depends on the user's specific board design.

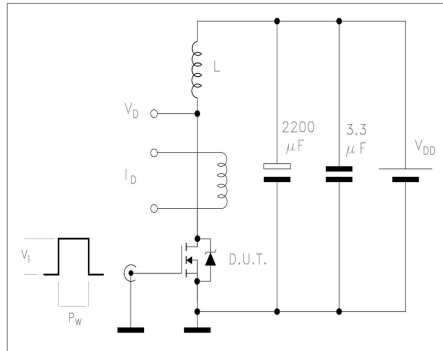
## Electrical Characteristics



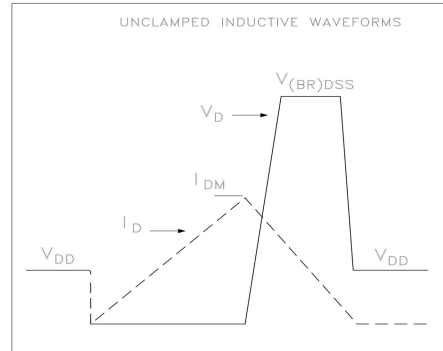


## Test Philosophy

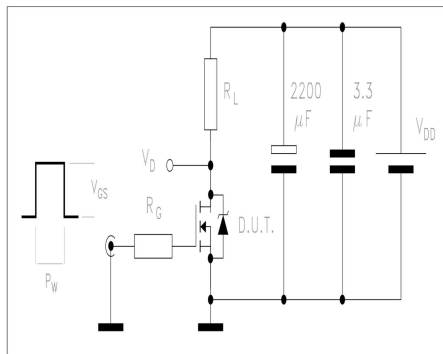
Unclamped Inductive Load Test Circuit



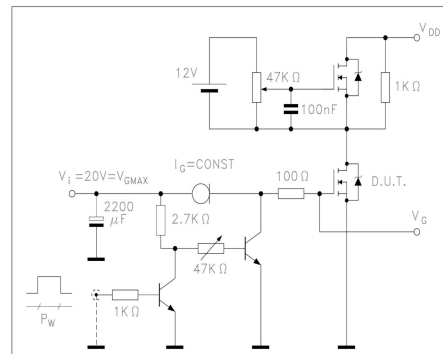
Unclamped Inductive Waveform



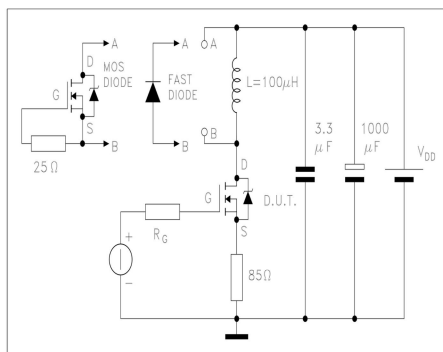
Switching Times Test Circuit For Resistive Load



Gate Charge test Circuit



Test Circuit For Inductive Load Switching And Diode Recovery Times



## Package Mechanical Data

